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PATENT

Atty. Dkt. No. APPM/5699/CMP/CMP/RKK

14 re Application of:

Chen, et al.

Serial No.: 10/038,066

Confirmation No.: 5741

Filed: January 3, 2002

**For: Planarization of Substrates
Using Electrochemical
Mechanical Polishing**

Group Art Unit: 1742

Examiner: Harry D. Wilkins, III

MAIL STOP NON-FEE AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATE OF MAILING

37 CFR 1.8

I hereby certify that this correspondence is being deposited on 3/4, 2004 with the United States Postal Service as First Class Mail in an envelope addressed to: NON-FEE AMENDMENT, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

3/4/04

Date _____

Signature

Dear Sir:

RESPONSE TO OFFICE ACTION DATED DECEMBER 4, 2003

In response to the Office Action dated December 4, 2003, having a shortened statutory period for response set to expire on March 4, 2004, please enter this response and reconsider the claims pending in the application for reasons discussed below. Although Applicant believes that no additional fees are due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/AMAT/5699/KMT, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

Amendments to the Specification begin on page 2 of this paper. **Amendments to the Claims** are reflected in the listing of claims which begins on page 4 of this paper. **Remarks** begin on page 11 of this paper.